

Abstract

The present invention aims to provide a wiring substrate highly reliable in insulation and connection and a method for manufacturing the wiring substrate. The wiring substrate comprises two or more wiring layers, insulation layers interposed between the neighboring wiring layers and containing an organic resin, and via formed in the insulation layers and extended between neighboring wiring layers. The via contain functional substances, as well as some of the voids (first voids) where at least the organic resins from the insulation layers exist and the remaining voids (second voids) where a gas exists. Consequently, so-called paste bleed, which is penetration of an insulation layer with a conductive paste, does not takes place and the elasticity modulus in the entire via becomes low and the flexibility is improved attributed to the second voids in the via. The expansion and the contraction well respond to the mechanical stress applied to the wiring substrate and thus disconnected of wiring layers hardly takes place and the reliability of electric and mechanical connection between the wiring layers is heightened.